

## Features

- Four Short-circuit-protected High-side Drivers with a Maximum Current Capability of 50 mA Each
- Four Short-circuit-protected Low-side Drivers with a Maximum Current Capability of 50 mA Each
- ON Resistance High Side  $R_{on} < 10\Omega$  Versus Total Temperature Range
- ON Resistance Low Side  $R_{on} < 7\Omega$  Versus Total Temperature Range
- Short-circuit Detection of Each Driver Stage
- Disabling of Driver Stages in the Case of Short-circuit and Overtemperature Detection
- Independent Control of Each Driver Stage via an 8-bit Shift Register
- Status Output Reports Short-circuit Condition
- Status Output Reports when All Loads Are Switched Off
- Timing of Status Output Reset Signalizes Failure Mode
- Temperature Protection in Conjunction with Short-circuit Detection



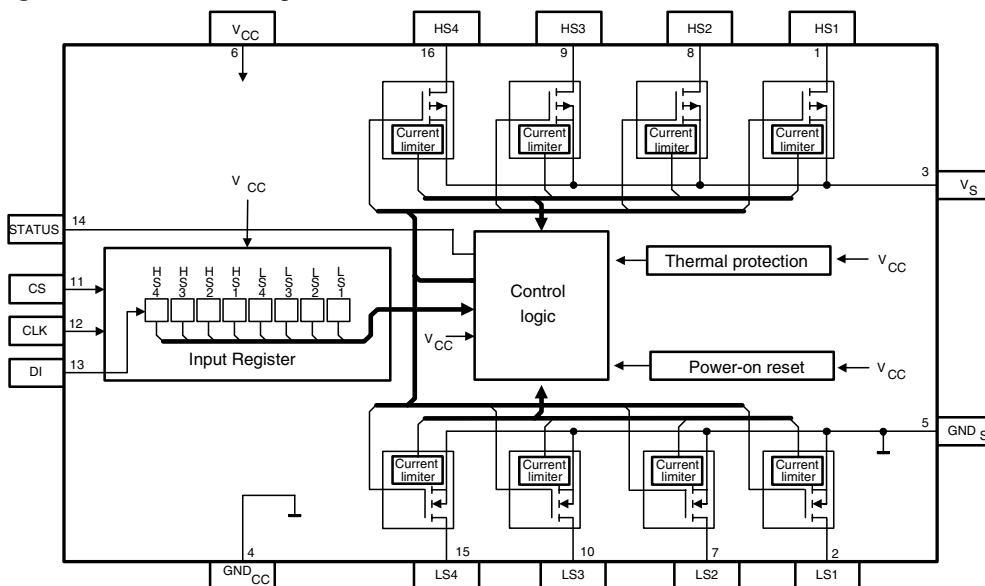
## Dual Quad BCDMOS Driver IC

## U6820BM

## 1. Description

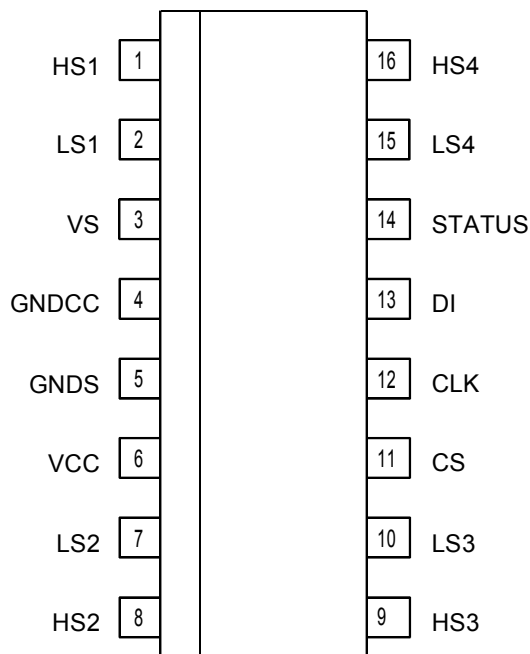
The U6820BM is a driver interface in BCDMOS technology with 8 independent driver stages having a maximum current capability of 50 mA each. Its partitioning into 4 high-side and 4 low-side driver stages allows an easy connection of either 4 half-bridges or 2 H-bridges on the pc board. The U6820BM communicates with a micro-controller via an 8-bit serial interface. Integrated protection against short circuit and overtemperature give added value. EMI protection and 2-kV ESD protection together with automotive qualification referring to conducted interference (ISO/TR 7637/1) make this IC ideal for both automotive and industrial applications.

**Figure 1-1.** Block Diagram



## 2. Pin Configuration

**Figure 2-1.** Pinning SO16



**Table 2-1.** Pin Description

| Pin | Symbol | Function  |
|-----|--------|---|
| 1   | HS1    | Output high side 1  |
| 2   | LS1    | Output low side 1   |
| 3   | VS     | Supply voltage 6V to 18V  |
| 4   | GNDCC  | Digital ground  |
| 5   | GNDS   | Power ground  |
| 6   | VCC    | Supply voltage 5V (external)  |
| 7   | LS2    | Output low side 2   |
| 8   | HS2    | Output high side 2  |
| 9   | HS3    | Output high side 3  |
| 10  | LS3    | Output low side 3   |
| 11  | CS     | Set supply status (chip select)   |
| 12  | CLK    | Clock line for 8-bit control shift register                                     |
| 13  | DI     | Data line for 8-bit control shift register                                      |
| 14  | STATUS | Status output (H = fault, diagnostic "H" if all driver stages are switched off) |
| 15  | LS4    | Output low side 4   |
| 16  | HS4    | Output high side 4  |

### 3. Description of the Control Interface to the Microcontroller

The serial-parallel interface basically includes an 8-bit shift register (SR), an 8-bit command register (CR) and a 4-bit counter.

The data input takes place with commands at pins DI (data input), CS (chip select) and CLK (clock). With a falling edge at CLK, the information at DI is transferred into the SR. The first information written into the SR is the least significant bit (LSB). The pin STATUS is used for diagnostic purposes and reports any fault condition to the microcontroller.

The input CS in accordance with the CR controls the serial interface. A high level at CS disables the SR. With a falling edge at CS, the SR is enabled. The CR control allows only the first 8 bits to be transferred into the SR, and further clocks at CLK are ineffective. If a rising edge occurs at CS after 8 clocks precisely, the information from the SR is transferred into the CR. If the number of clock cycles during the low phase of CS was less or more than eight transitions, no transfer will take place. A new command switches the output stages on or off immediately.

Each output stage is controlled by one specific bit of the CR. Low level means "supply off" or inactive, and high level means "supply on" or active. If all 8 bits are at a low level, the output stages will be set into standby mode.

If one of the output stages detects a short circuit and additionally overtemperature condition, the corresponding control bit in the CR is set to low. This reset has priority over an external command to CR, thus, this does not affect the 1<sup>st</sup> control bit. The priority protects the IC against overtemperature by activating the temperature shut down immediately.

### 4. The STATUS Output

The STATUS output is at low level during normal operation. If one or more output stages detect short circuit or if overtemperature is indicated, the STATUS output changes to high level (OR-connection).

For diagnostic purposes (self test of the status output), the status output can also be brought into high level during standby mode.

#### 4.1 Timing of the Status Output Reset Signalizes the Failure Mode

The use of different reset conditions at the STATUS output simplifies the failure analysis during normal operation, and is also beneficial during testing.

The storage content can be used for STATUS output. It is indicated and latched immediately with the rising edge of CS at STATUS output if less than 8 clocks were received during the low phase of CS. The reset is initiated by the falling edge of the 8<sup>th</sup> clock (bit 7) of the next data input.

Also, the appearance of more than 8 clocks is latched and indicated at STATUS by the rising edge of the 9<sup>th</sup> clock. The reset is initiated by the falling edge of the 2<sup>nd</sup> clock (bit 1) of the next data input.

The detection of overtemperature is latched internally. It is reset by the falling edge of the 4<sup>th</sup> clock (bit 3) of a data transfer if overtemperature is no longer present.

## 4.2 Power-on Reset

After switching on the supply voltage, all data latches are reset and the outputs are switched off. The typical power-on reset threshold is  $V_{CC} = 3.7V$ . The outputs are activated after the first data transfer.

## 4.3 Short-circuit Protection

The current of the output stages is limited by an active feedback control. Short circuit at one output stage sets the diagnostic pin 14 (STATUS) to high. In case of both conditions, short circuit at one of the outputs and temperature detection, the affected output is switched off selectively. It will be activated again after the first new data transfer.

## 4.4 Inductance Protection

Clamping diodes and FETs are integrated to protect the IC against too high or too low voltages at the outputs. They prevent the IC from latch up and parasitic currents which may exceed power dissipation.

## 4.5 Temperature Protection

The IC is protected by an overtemperature detection. As soon as the junction temperature  $T_j = 155^\circ C$  typically is exceeded, the diagnostic pin 14 (STATUS) is set "high". General overtemperature detection along with short-circuit condition at a specific output result in temperature shut down at that specific output. After temperature shut down, the data input register has to be set again with a hysteresis of typically  $\Delta T = 15K$  ( $T_j = 140^\circ C$ ).

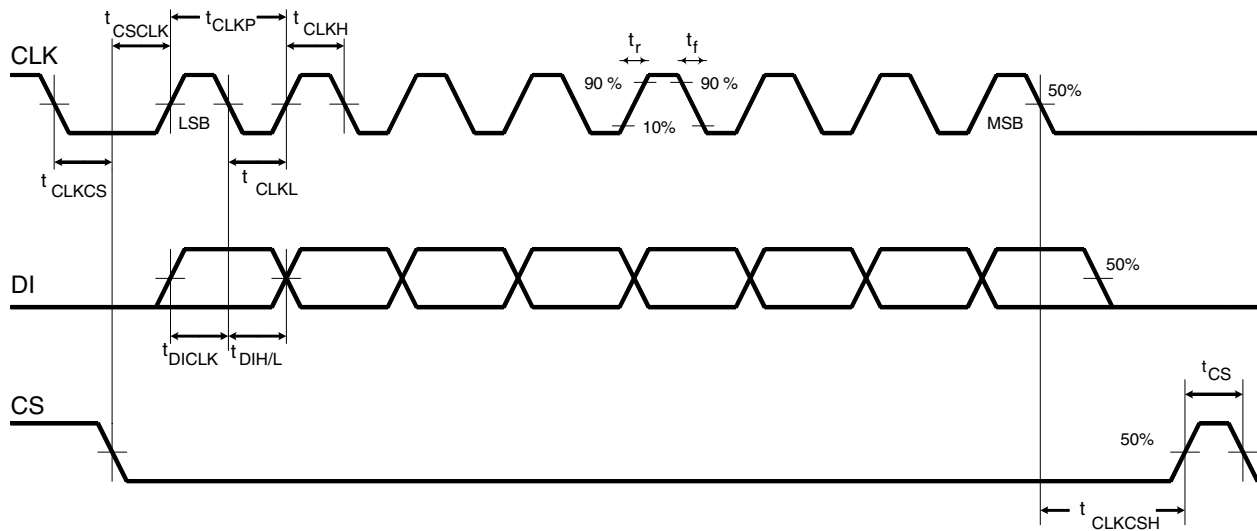
## 4.6 ESD Protection

All output stages are protected against electrostatic discharge up to 5 kV (HBM) with external components (see [Figure 8-1](#)), all other pins are protected up to 2 kV (HBM).

**Table 4-1.** Timing of the STATUS Output

| Shift Register                    | Command Register                  | Condition                | Low-side Switch |     |     |     | High-side Switch |     |     |     | Status |          |
|-----------------------------------|-----------------------------------|--------------------------|-----------------|-----|-----|-----|------------------|-----|-----|-----|--------|----------|
|                                   |                                   |                          | LS1             | LS2 | LS3 | LS4 | HS1              | HS2 | HS3 | HS4 | Set    | Reset    |
| 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0   | 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0   | All out = OK             | off             | off | off | off | off              | off | off | off | H      | New CS   |
| 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1   | 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1   | All on = OK              | on              | on  | on  | on  | on               | on  | on  | on  | L      |          |
| 0 0 0 0 0 0 0 0 1 0 0 0 0 0 0 0 1 | 0 0 0 0 0 0 0 0 1 0 0 0 0 0 0 0 1 | E.g. one on = OK         | off             | off | off | off | off              | off | off | on  | L      |          |
| 0 1 1 1 1 1 1 1 1 0 1 1 1 1 1 1 1 | 0 1 1 1 1 1 1 1 1 0 1 1 1 1 1 1 1 | Short at LS3             | off             | on  | on  | on  | on               | on  | on  | on  | H      | No short |
| 1 1 1 1 1 1 1 1 1 1 1 1 0 1 1 1 1 | 1 1 1 1 1 1 1 1 1 1 1 1 0 1 1 1 1 | Temp & short at HS4      | on              | on  | on  | off | on               | on  | on  | on  | H      | New CS4  |
| 1 1 0 0 0 0 0 1 1 0 0 0 0 0 0 0 0 | 1 1 0 0 0 0 0 1 1 0 0 0 0 0 0 0 0 | $V_{VCC} < 3.7 V = P-ON$ | off             | off | off | off | off              | off | off | off | H      | P-ON, CS |
| 1 1 1 0 0 0 1 1 x x x x x x x x   | 1 1 1 0 0 0 1 1 x x x x x x x x   | CS with less 8 CLK       | x               | x   | x   | x   | x                | x   | x   | x   | H      | New CS 8 |
| 0 0 0 1 1 1 0 0 x x x x x x x x   | 0 0 0 1 1 1 0 0 x x x x x x x x   | CS with more 8 CLK       | x               | x   | x   | x   | x                | x   | x   | x   | H      | New CS 2 |

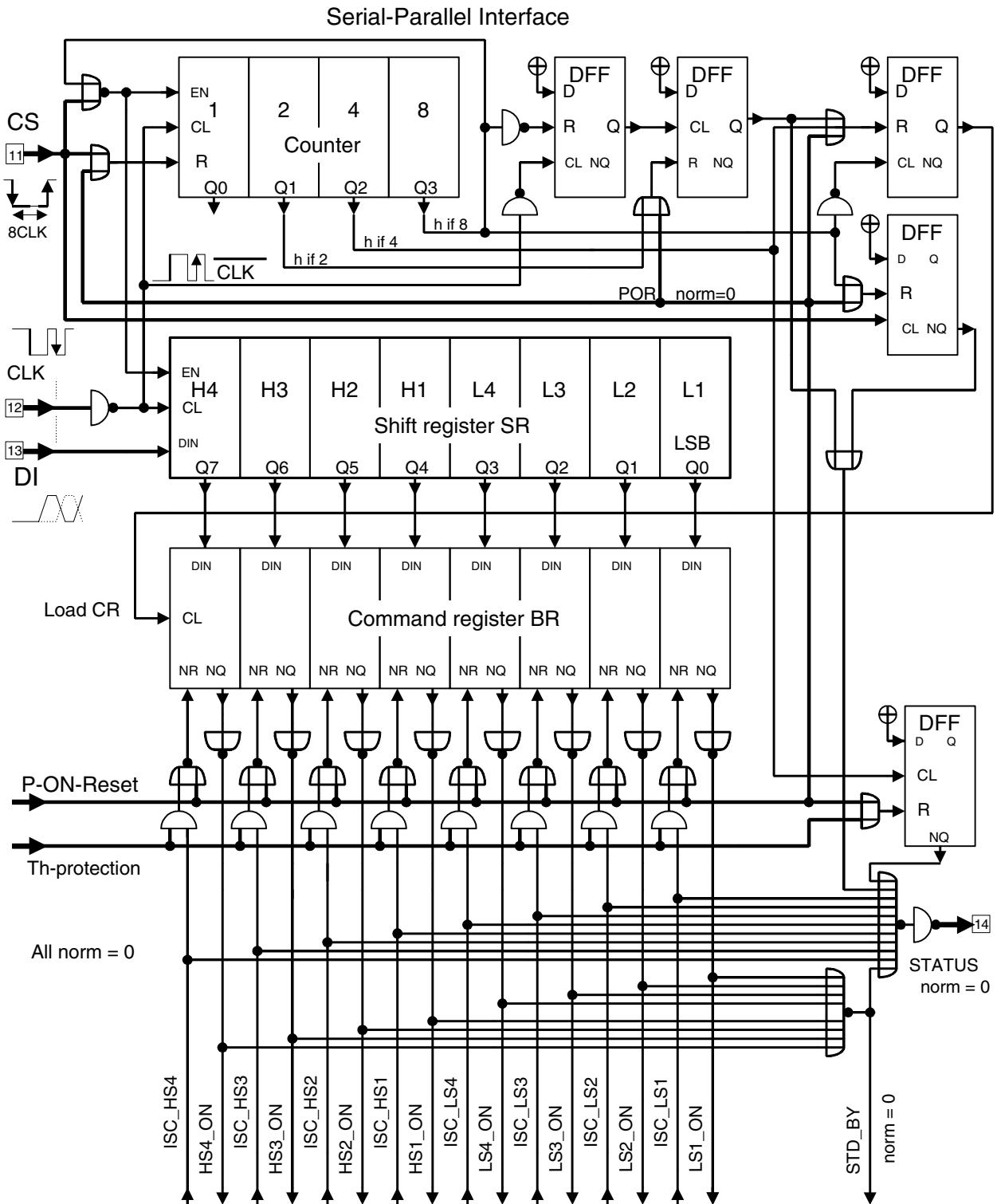
**Figure 4-1.** Data Transfer Timing Diagram



**Table 4-2.** AC Characteristics for Testing

| Specification | Conditions                            | Minimum | Maximum | Unit |
|---------------|---------------------------------------|---------|---------|------|
| $t_r$ (rise)  | 10% to 90% $V_{CC}$ on CLK, DI and CS |         | 10      | ns   |
| $t_f$ (fall)  | 10% to 90% $V_{CC}$ on CLK, DI and CS |         | 10      | ns   |
| $t_{CLKP}$    | $1/2 V_{CC}$                          | 250     |         | ns   |
| $t_{CLKH}$    | $1/2 V_{CC}$                          | 100     |         | ns   |
| $t_{CLKL}$    | $1/2 V_{CC}$                          | 100     |         | ns   |
| $t_{CLKCS}$   | $1/2 V_{CC}$                          | 150     |         | ns   |
| $t_{CSCLK}$   | $1/2 V_{CC}$                          | 100     |         | ns   |
| $t_{DCLK}$    | $1/2 V_{CC}$                          | 80      |         | ns   |
| $t_{DIH/L}$   | $1/2 V_{CC}$                          | 100     |         | ns   |
| $t_{CLKCSH}$  | $1/2 V_{CC}$                          | 100     |         | ns   |
| $t_{CS}$      | $1/2 V_{CC}$                          | 250     |         | ns   |

**Figure 4-2.** Block Diagram of the Control Interface



## 5. Absolute Maximum Ratings

Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

| Parameters                          | Pin              | Symbol                      | Minimum | Maximum         | Unit |
|-------------------------------------|------------------|-----------------------------|---------|-----------------|------|
| Supply voltage                      | 3                | $V_{VS}$                    | −0.3    | +40             | V    |
| Logic supply voltage                | 6                | $V_{VCC}$                   | −0.3    | +7              | V    |
| Logic input voltage                 | 11, 12, 13       | CS, CLK, DI                 | −0.3    | $V_{VCC} + 0.5$ | V    |
| Logic output voltage                | 14               | STATUS                      | −0.3    | $V_{VCC} + 0.3$ | V    |
| Input current                       | 3                | $I_{VS}$                    |         | 0.2             | mA   |
|                                     | 6                | $I_{VCC}$                   |         | 5               | mA   |
| Output current (internally limited) | 1-2, 8-11, 15-16 | $I_{1H-4H}$ and $I_{1L-4L}$ | 30      | 65              | mA   |
| Junction temperature range          |                  | $T_j$                       | −40     | +150            | °C   |
| Storage temperature range           |                  | $T_{stg}$                   | −55     | +150            | °C   |

## 6. Thermal Resistance

| Parameters       | Symbol     | Value | Unit |
|------------------|------------|-------|------|
| Junction ambient | $R_{thJA}$ | 110   | K/W  |
| Junction case    | $R_{thJC}$ | 26    | K/W  |

## 7. Operating Range

| Parameters                       | Pin        | Symbol      | Value                                       | Unit |
|----------------------------------|------------|-------------|---|------|
| Supply voltage                   | 3          | $V_{VS}$    | 6 to 18                                     | V    |
| Logic supply voltage             | 6          | $V_{VCC}$   | 4.5 to 5.5                                  | V    |
| Logic input voltage low          | 11, 12, 13 | CS, CLK, DI | −0.2 to $(0.2 \times V_{VCC})$              | V    |
| Logic input voltage high         | 11, 12, 13 | CS, CLK, DI | $(0.7 \times V_{VCC})$ to $(V_{VCC} + 0.3)$ | V    |
| Logic output voltage (1 mA load) | 14         | STATUS      | 0.5 to $(V_{VCC} - 1)$                      | V    |
| Clock frequency                  |            | $f_{CLK}$   | 5   | MHz  |
| Junction temperature range       |            | $T_j$       | −40 to +150                                 | °C   |

## 8. Electrical Characteristics

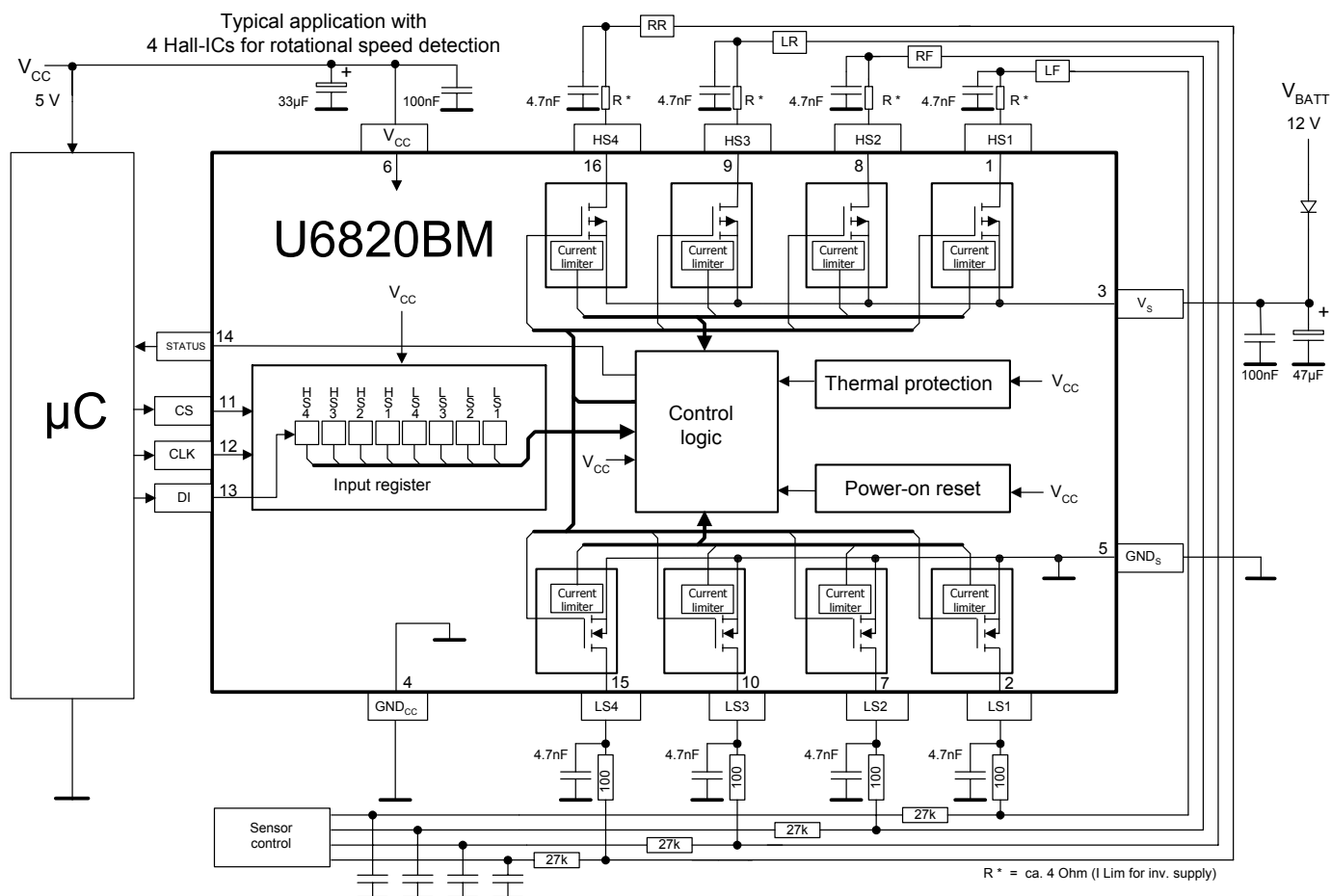
7V < V<sub>VS</sub> < 40V; 4.5V < V<sub>VCC</sub> < 5.5V; -40°C < T<sub>j</sub> < 150°C; unless otherwise specified

| No.      | Parameters   | Test Conditions                                     | Pin                    | Symbol                  | Min.                     | Typ. | Max.                     | Unit  | Type* |
|----------|--|---|------------------------|-------------------------|--------------------------|------|--------------------------|-------|-------|
| <b>1</b> | <b>Current Consumption</b>                         |   |                        |                         |                          |      |                          |       |       |
| 1.1      | Supply current VS                                  | No external load                                    | 3                      | I <sub>VS</sub>         |                          |      | 0.2                      | mA    | A     |
| 1.2      | Supply current VCC                                 | No external load                                    | 6                      | I <sub>VCC</sub>        |                          |      | 5                        | mA    | A     |
| 1.3      | Power-on reset threshold                           |   | 6                      | V <sub>CC POR</sub>     | 3.4                      | 3.7  | 4.0                      | V     | A     |
| 1.4      | Power-on reset delay time                          | After switching on V <sub>CC</sub>                  | 6                      | T <sub>d POR</sub>      | 60                       | 95   | 130                      | μs    | D     |
| <b>2</b> | <b>Thermal Shutdown</b>                            |   |                        |                         |                          |      |                          |       |       |
| 2.1      | Thermal shutdown set                               |   |                        | t <sub>j PW set</sub>   | 140                      | 155  | 165                      | °C    | A     |
| 2.2      | Thermal shutdown reset                             |   |                        | t <sub>j PW reset</sub> | 130                      | 135  | 155                      | °C    | A     |
| 2.3      | Thermal hysteresis                                 |   |                        | Dt                      |                          | 20   |                          | K     | A     |
| <b>3</b> | <b>Output Specifications (1L - 4L, 1H - 4H)</b>    |   |                        |                         |                          |      |                          |       |       |
| 3.1      | On-resistance low                                  | I <sub>out</sub> = 26 mA,<br>T <sub>j</sub> = 125°C | 2, 7,<br>10, 15        | R <sub>DSONLOW</sub>    | 3                        | 4    | 7                        | Ω     | A     |
| 3.2      | On-resistance high                                 | I <sub>out</sub> = 26 mA,<br>T <sub>j</sub> = 125°C | 1, 8,<br>9, 16         | R <sub>DSONHIGH</sub>   | 4                        | 6.25 | 10                       | Ω     | A     |
| 3.3      | Output leakage current lowside                     | V <sub>LSIDE 1-4</sub> = 17.5V                      | 2, 7,<br>10, 15        | I <sub>LOWSIDE</sub>    |                          |      | 5                        | μA    | A     |
| 3.4      | Output leakage current highside                    | V <sub>HSIDE 1-4</sub> = 0.5V                       | 1, 8,<br>9, 16         | I <sub>HIGHSIDE</sub>   |                          |      | -5                       | μA    | A     |
| 3.5      | Output leakage steepness                           |   | 1-2,<br>7-10,<br>15-16 | dV <sub>OUT</sub> /dt   | 50                       | 200  | 400                      | mV/μs | D     |
| 3.6      | Over current limitation highside                   |   | 1, 8,<br>9, 16         | I <sub>HIGHSIDE</sub>   | 27                       | 45   | 95                       | mA    | A     |
| 3.7      | Over current limitation lowside                    |   | 2, 7,<br>10, 15        | I <sub>LOWSIDE</sub>    | 27                       | 45   | 80                       | mA    | A     |
| <b>4</b> | <b>Serial Interface – Inputs: CS, CLK and DATA</b> |   |                        |                         |                          |      |                          |       |       |
| 4.1      | Input voltage low level threshold                  |   | 11-13                  | V <sub>ILOW</sub>       |                          |      | 0.2×<br>V <sub>VCC</sub> | V     | A     |
| 4.2      | Input voltage high level threshold                 |   | 11-13                  | V <sub>IHIGH</sub>      | 0.7×<br>V <sub>VCC</sub> |      |                          | V     | A     |
| 4.3      | Hysteresis of input voltage                        |   | 11-13                  | ΔV <sub>i</sub>         |                          | 300  |                          | mV    | A     |
| 4.4      | Pull-down current                                  | (internal pull-up resistor:<br>30 kΩ to 140 kΩ)     | 11-13                  | I <sub>i</sub>          |                          |      | 300                      | μA    | A     |
| <b>5</b> | <b>Serial Interface – Output: STATUS</b>           |   |                        |                         |                          |      |                          |       |       |
| 5.1      | Output voltage low level                           | I = 1 mA  |                        | V <sub>OLOW</sub>       |                          |      | 0.5                      | V     | A     |
| 5.2      | Output voltage high level                          | I = 1 mA  |                        | V <sub>OHIGH</sub>      | V <sub>VCC</sub> - 1     |      | V <sub>VCC</sub>         | V     | A     |

\*) Type means: A = 100% tested, B = 100% correlation tested, C = Characterized on samples, D = Design parameter



**Figure 8-1. Application Circuit**



**Note:** It is strongly recommended to connect the blocking capacitors at  $V_S$  and  $V_{CC}$  as close as possible to the power supply and GND pins. Recommended value for  $V_S$  is less than 100  $\mu\text{F}$  electrolytic in parallel with 100 nF ceramic. Value for electrolytic capacitor depends on external loads, noise and surge immunity efforts. Recommended value for  $V_{CC}$  is 33  $\mu\text{F}$  electrolytic in parallel with 100 nF ceramic. The 4- $\Omega$  resistors connected to the pins HS1 - HS4 support the protection in case of a short circuit of these pins to  $V_{Batt}$ .

| Extended Type Number | Package | Remarks                   |
|----------------------|---------|---------------------------|
| U6820BM-MFPG3Y       | SO16    | Taped and reeled, Pb-free |

**SO16**  
Dimensions in mm

The technical drawing shows three views of the SO16 connector. The top view shows a rectangular component with 16 pins, 8 on each side, with dimensions 10.0, 9.85, 8.89, 1.4, 0.25, 0.10, 0.4, and 1.27. The side view shows the profile with dimensions 5.2, 4.8, 3.7, 3.8, 6.15, 5.85, and 0.2. The front view shows the component with pins numbered 1 to 16. A note indicates technical drawings according to DIN specifications.

16 9

1 8

technical drawings  
according to DIN  
specifications

| Revision No.    | History  |
|-----------------|--|
| 4527B-BCD-09/05 | <ul style="list-style-type: none"> <li>• Put datasheet in a new template</li> <li>• Pb-free logo on page 1 added</li> <li>• New heading rows on Table “Absolute Maximum Ratings” on page 7 added</li> <li>• Table “Ordering Information” on page 10 changed</li> </ul> |



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